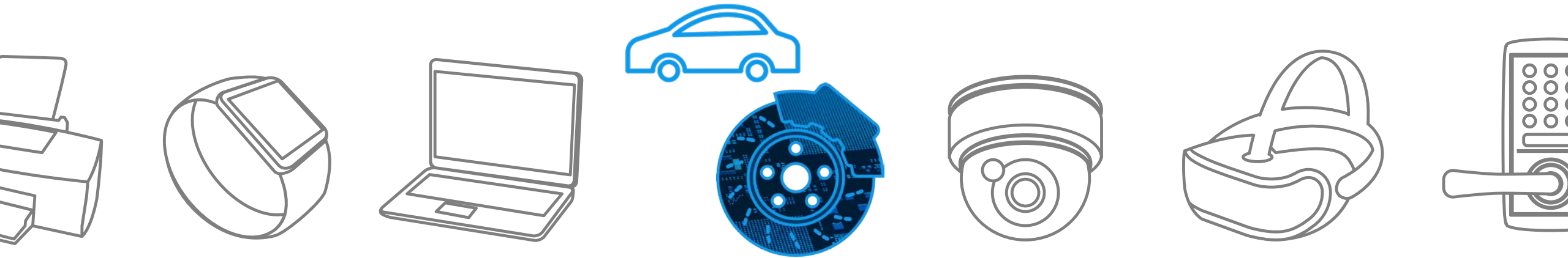
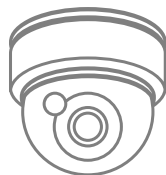
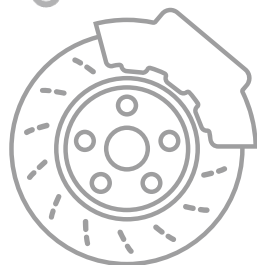


Automotive Brake Control

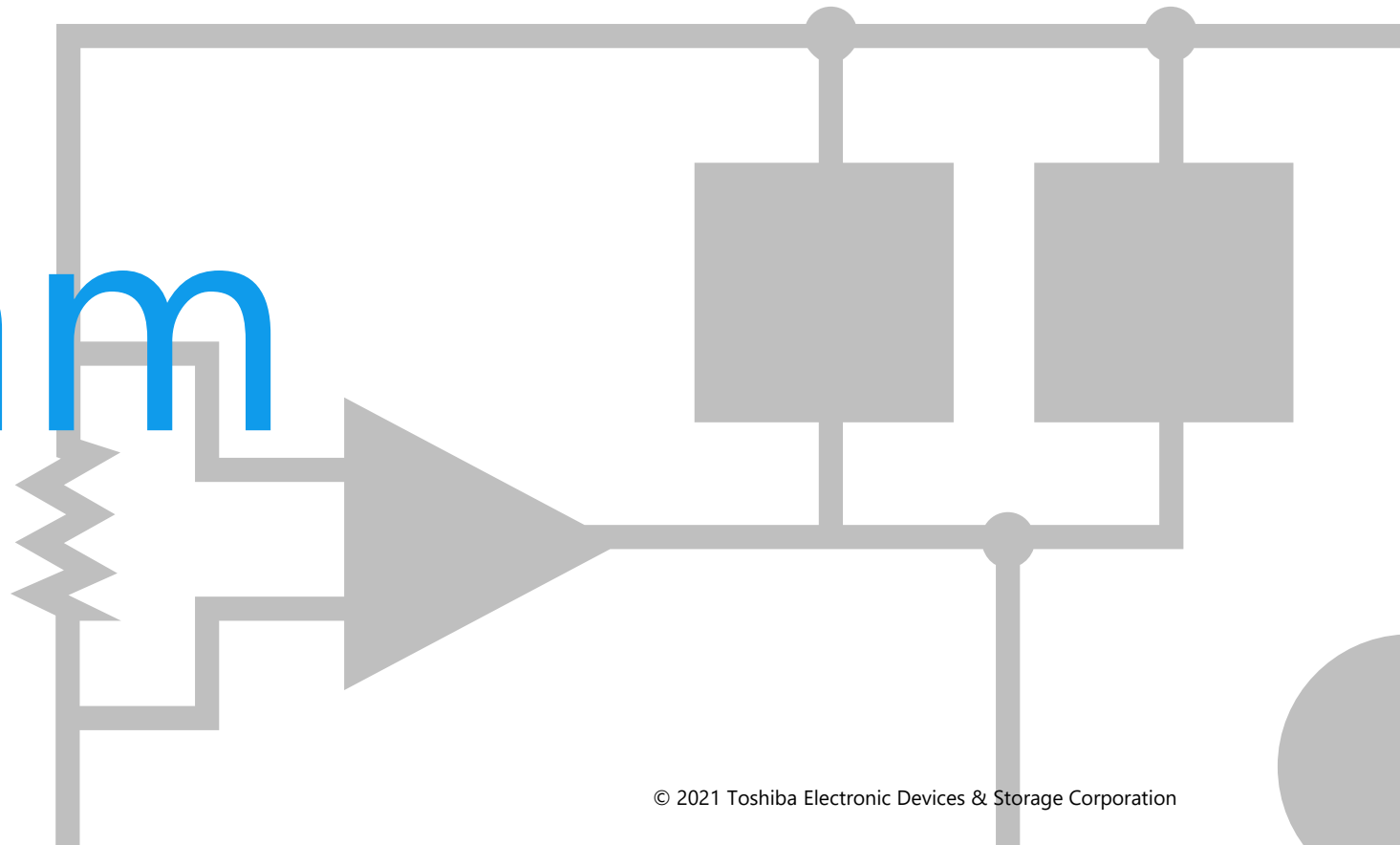
Solution Proposal by Toshiba



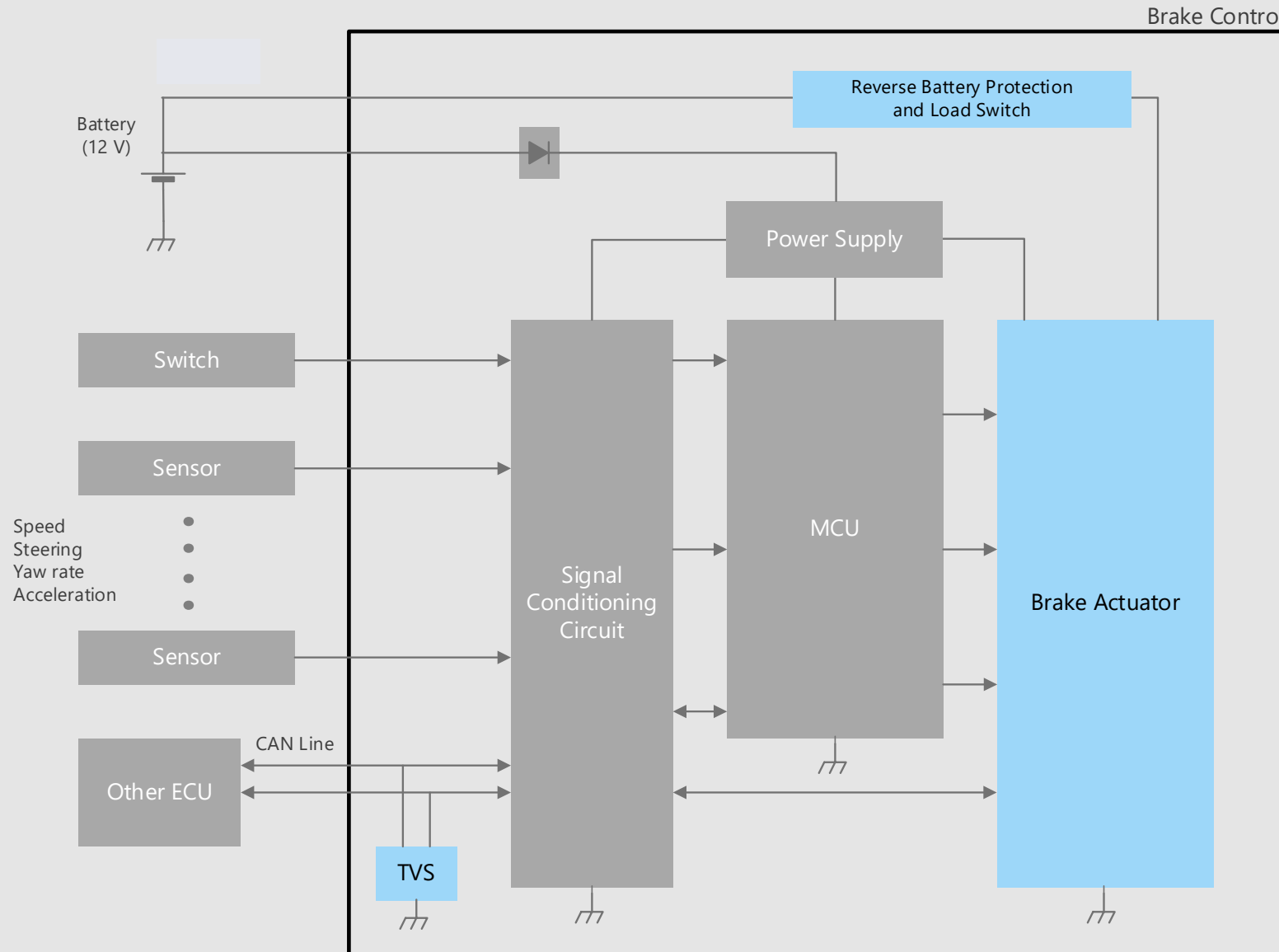


Toshiba Electronic Devices & Storage Corporation provides comprehensive device solutions to customers developing new products by applying its thorough understanding of the systems acquired through the analysis of basic product designs.

Block Diagram

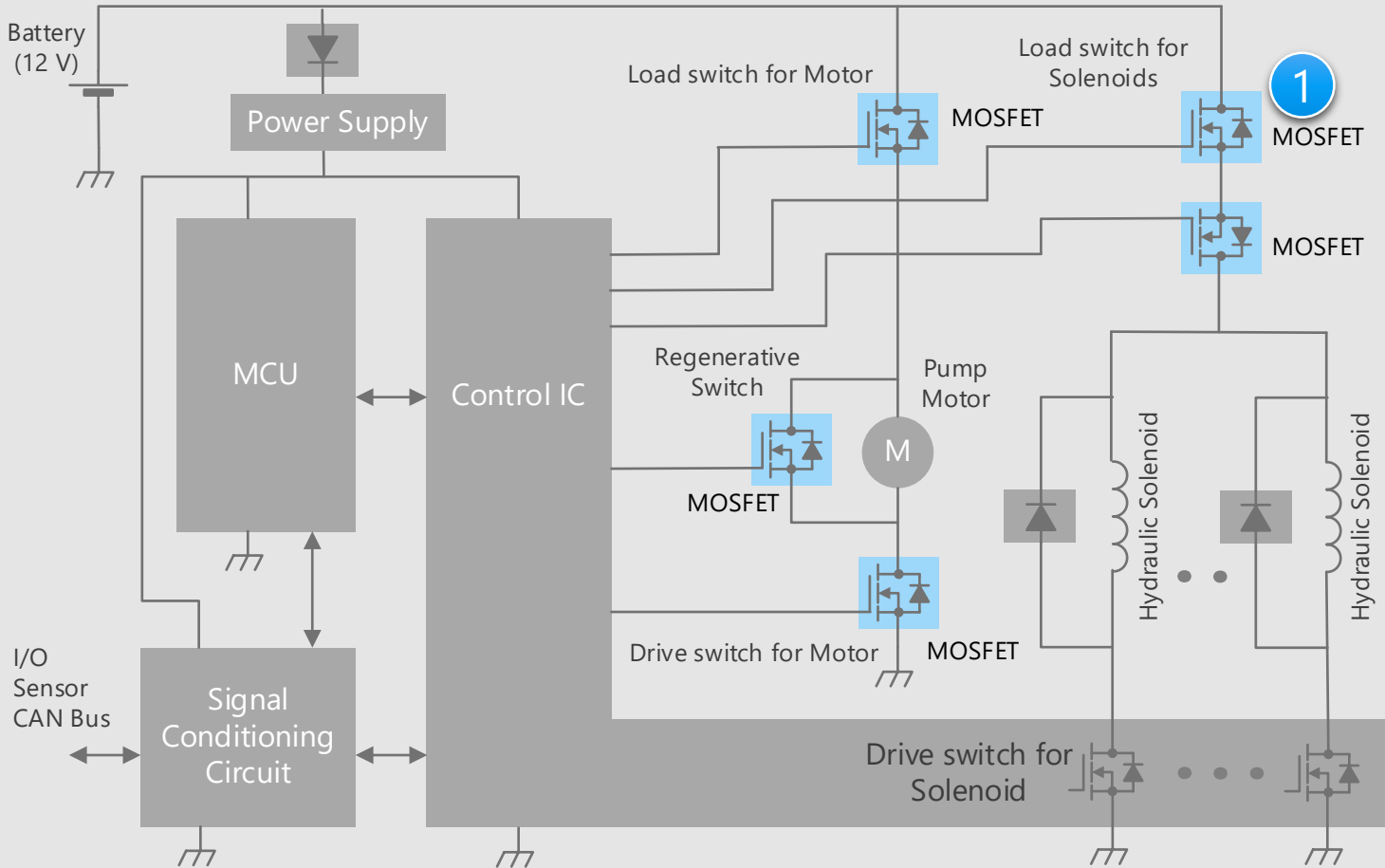


Brake Control Overall block diagram



Brake Control Detail of brake actuator

Brake actuator for ABS/ESC



* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

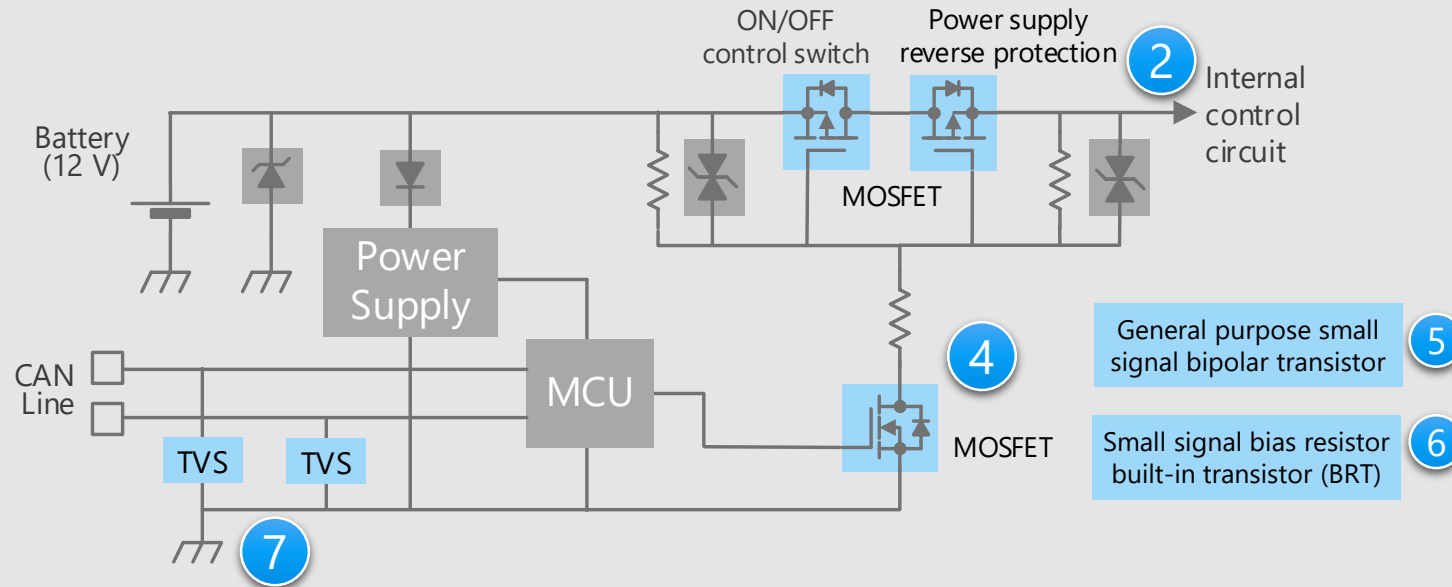
Criteria for device selection

- It is necessary to select the product with the suitable voltage and current ratings for each application.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

- **Low on-resistance contributes low power consumption of the system**
U-MOS Series 40 V N-ch MOSFET

Power supply ON/OFF control and reverse connection protection circuit (P-ch type)



Criteria for device selection

- It is necessary to select the product with the suitable voltage and current ratings for each application.
- It is necessary to select a gate driver according to the characteristics of the switching device to be driven.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

- **Low on-resistance contributes low power consumption of the system**

U-MOS Series -40 V / -60 V P-ch MOSFET

- **Extensive product lineup**

General purpose small signal MOSFET

General purpose small signal bipolar transistor

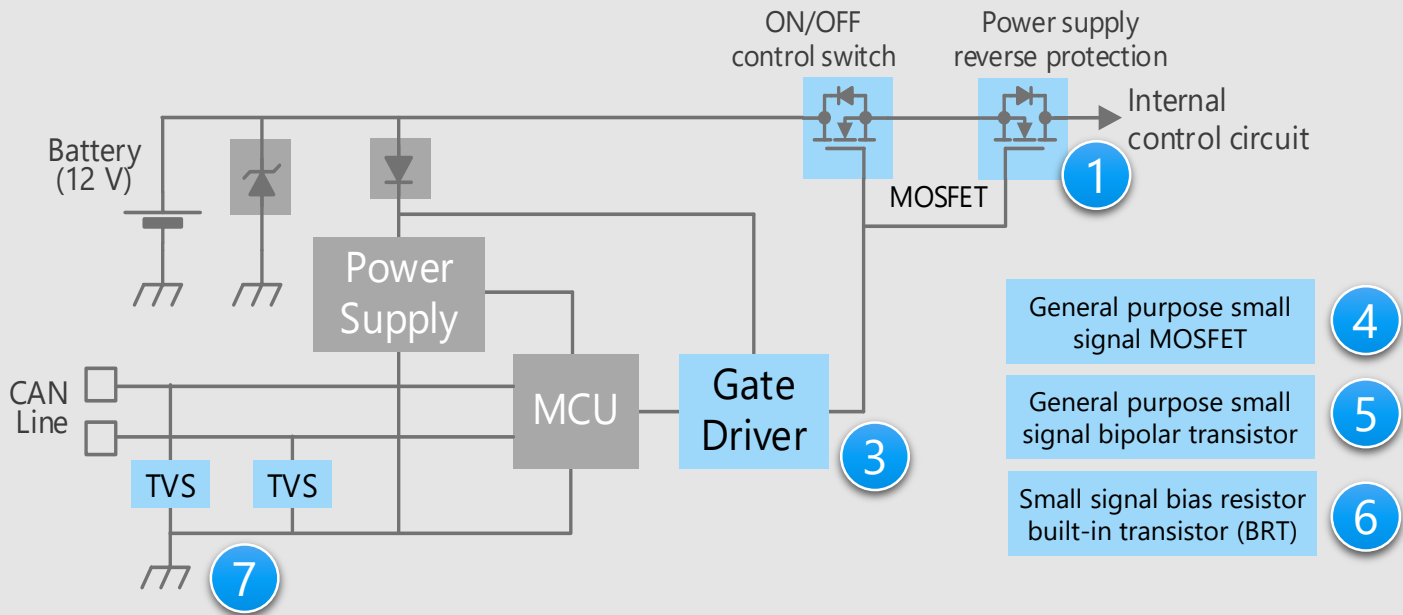
Small signal bias resistor built-in transistor (BRT)

- **Suitable for ESD protection**

TVS diode (for CAN communication)

* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Power supply ON/OFF control and reverse connection protection circuit (N-ch type)



Criteria for device selection

- It is necessary to select the product with the suitable voltage and current ratings for each application.
- It is necessary to select a gate driver according to the characteristics of the switching device to be driven.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

- **Low on-resistance contributes low power consumption of the system**

U-MOS Series 40V N-ch MOSFET

- **Gate driver with protection and diagnosis functions**

Gate driver (for switch)

- **Extensive product lineup**

General purpose small signal MOSFET

General purpose small signal bipolar transistor

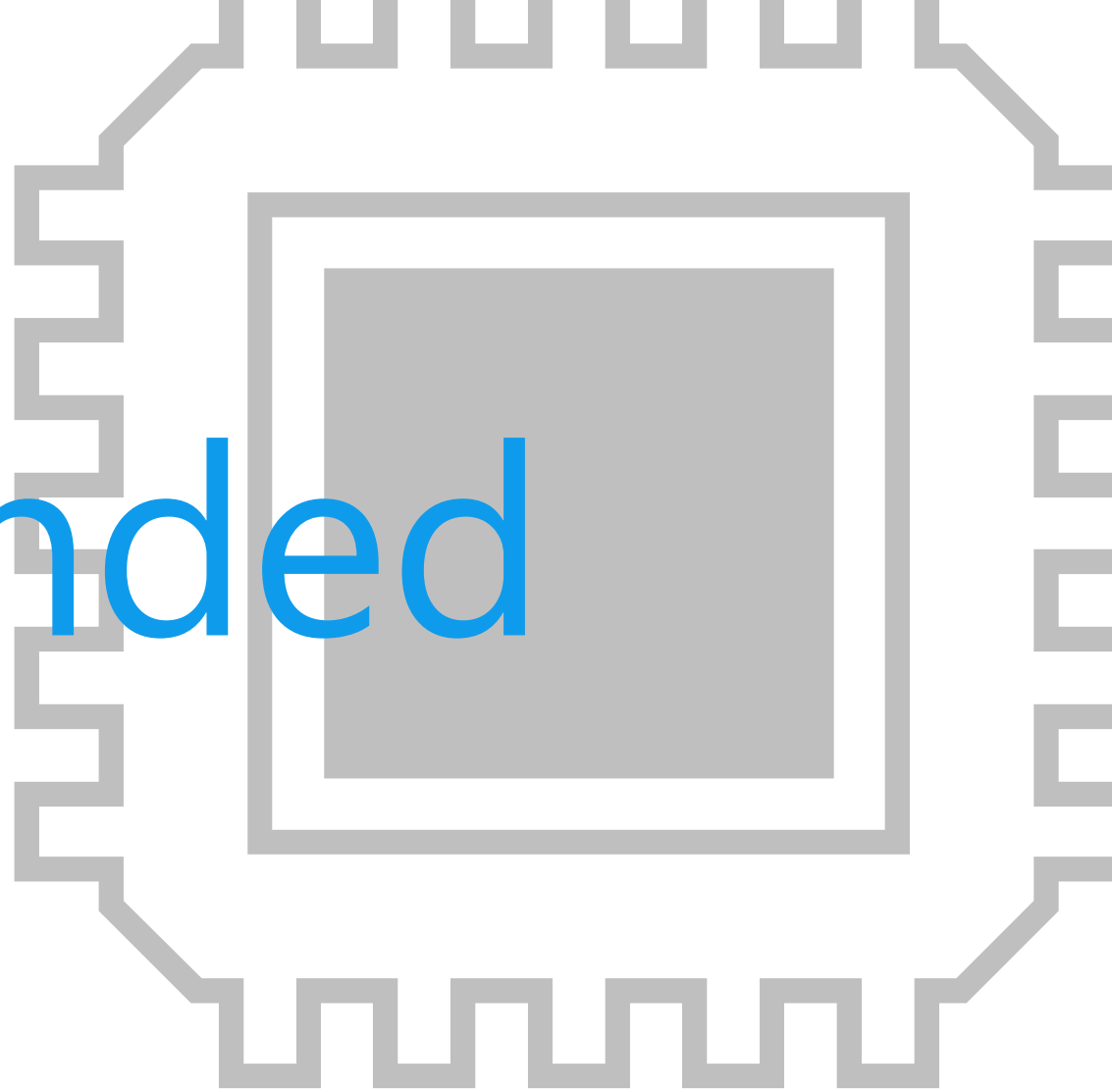
Small signal bias resistor built-in transistor (BRT)

- **Suitable for ESD protection**

TVS diode (for CAN communication)

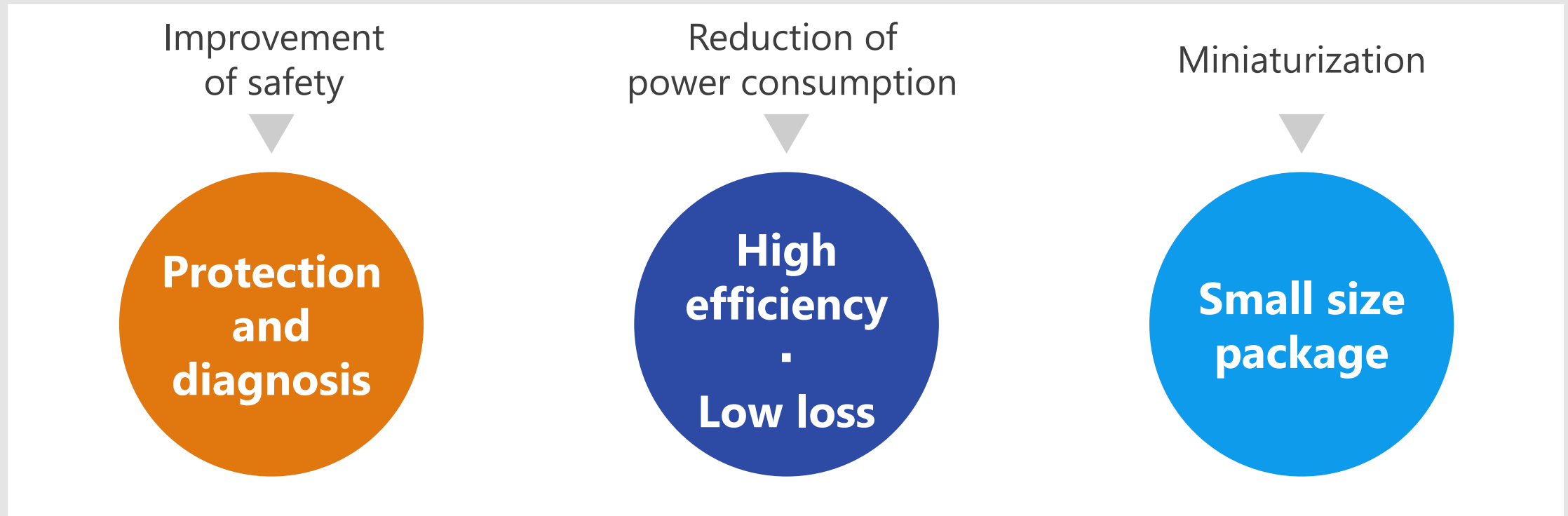
* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Recommended Devices



Device solutions to address customer needs

As described above, in the design of brake control, “**Improvement of safety**”, “**Reduction of power consumption**” and “**Miniaturization**” are important factors. Toshiba’s proposals are based on these three solution perspectives.



Device solutions to address customer needs

Protection
and
diagnosis

High
efficiency
·
Low loss

Small size
package

①	U-MOS Series 40 V N-ch MOSFET	●	●
②	U-MOS Series -40 V / -60 V P-ch MOSFET	●	●
③	Gate driver (for switch)	●	●
④	General purpose small signal MOSFET	●	●
⑤	General purpose small signal bipolar transistor		●
⑥	Small signal bias resistor built-in transistor (BRT)		●
⑦	TVS diode (for CAN communication)	●	●

Value provided

The advanced U-MOSIX-H processes enables low on-resistance and low noise, thereby reducing power consumption.

1 Low loss (reduced on-resistance)

Using low on-resistance technology to contribute to reduced power consumption systems.
On-resistance of 61 % reduction per unit area. (compared to U-MOSIV)

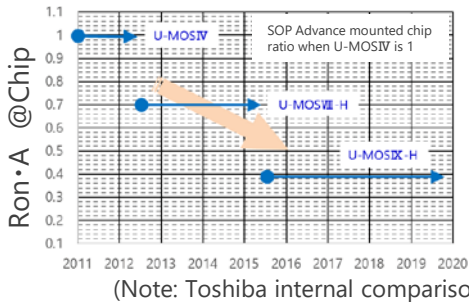
2 Compact and low loss package

By adopting a Cu connector structure and a double-sided heat dissipation structure, low loss and high heat dissipation are realized.
Wettable Frank (WF) package contributes good mountability.

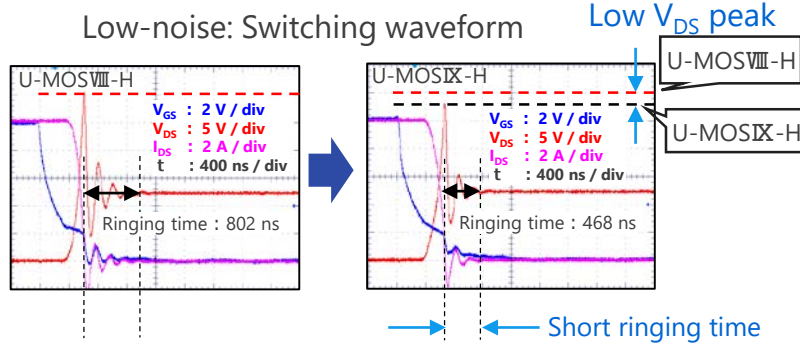
3 Low noise (low EMI)

Improved chip process reduces surge voltage and ringing time.

Low Loss: RonA Trend



Low-noise: Switching waveform

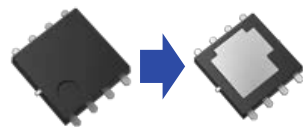


TO-220SM(W) Cu connector design









Package resistance is reduced by 64 %, compared to D2PAK+.

DSOP Advance(WF)L double-sided cooling package



Thermal resistance is reduced by 76 % @t = 3 s, mounted on board compared to SOP Advance(WF).

Line up			
Part number	Drain current	On-resistance (Max) @V _{GS} = 10 V	Package
XPN3R804NC	40 A	3.8 mΩ	TSON Advance(WF) 
TK1R4S04PB	120 A	1.35 mΩ	DPAK+ 
TPHR7904PB	150 A	0.79 mΩ	SOP Advance(WF) 
TPWR7904PB	150 A	0.79 mΩ	DSOP Advance(WF)L 
TKR74F04PB	250 A	0.74 mΩ	TO-220SM(W) 
TK1R5R04PB	160 A	1.5 mΩ	D2PAK+ 

Value provided

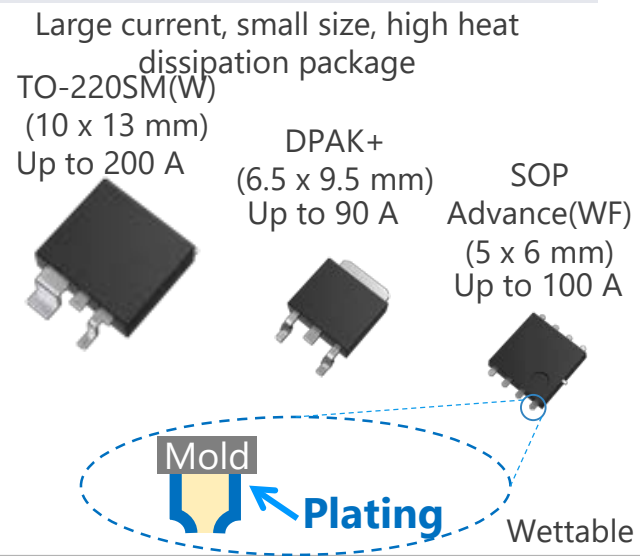
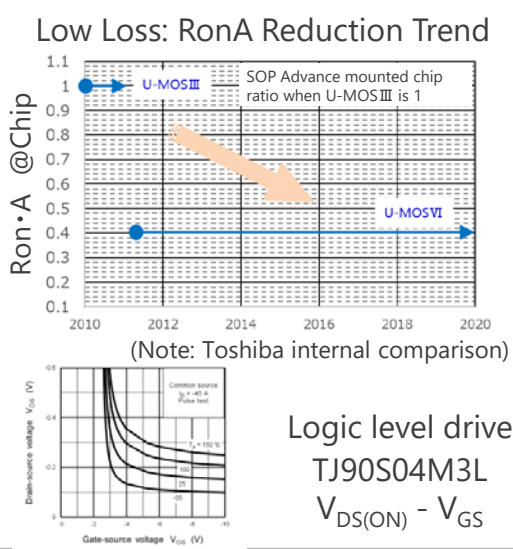
Low on-resistance contributes to reduce system power consumption.

1 Low loss (reduced on-resistance) and logic level drive




Using low on-resistance technology contributes to reduce system power consumption.
Lineups of logic level drive type are supported.

2 Small surface mount package developed

By adopting a Cu connector structure and a double-sided heat dissipation structure, low loss and high heat dissipation are realized.
Wettable Frank (WF) package contributes good mountability.



Line up

Part number	Drain-source Voltage	Drain current	On-resistance (Max) @V _{GS} = -10 V	Package
TJ90S04M3L	-40 V	-90 A	4.3 mΩ	DPAK+ 
TJ60S06M3L	-60 V	-60 A	11.2 mΩ	
XPH3R114MC	-40 V	-100 A	3.1 mΩ	SOP Advance(WF) 
TJ200F04M3L	-40 V	-200 A	1.8 mΩ	TO-220SM(W) 

[Return to Block Diagram TOP](#)

3 Gate driver (for switch)

TPD7104AF / TPD7106F / TPD7107F

Protection and diagnosis

High efficiency
Low loss

Small size package

Value provided

A charge pump circuit for the N-channel MOSFET gate drive is built in, allowing for easy semiconductor relay configuration.

1 Built-in charge pump circuit

Built-in charge pump circuit enables N-channel MOSFET as high side switch.
Easy to configure a semiconductor relay.

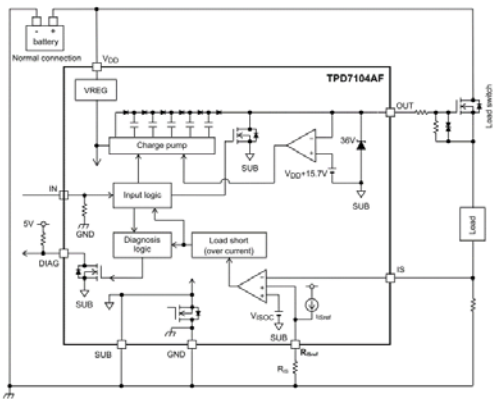
2 Can be controlled by logic level voltage

It is possible that Direct control by output signal of MCUs or CMOS logic ICs.

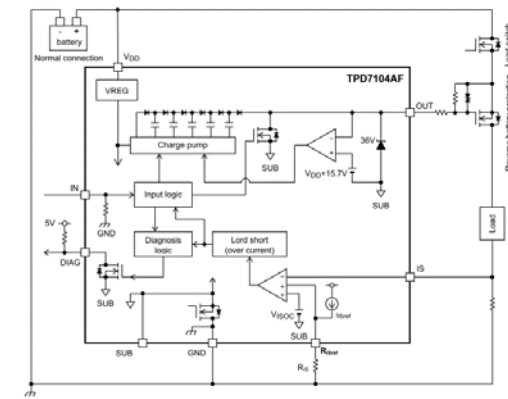
3 Small package

The small surface mount packages such as PS-8, SSOP16 and WSON10A contribute to the miniaturization of system.

Semiconductor relay (switch) application (TPD7104AF)






Power supply reverse connection protection MOSFET control (TPD7104AF)



Back to back configuration

Line up

Part number	TPD7104AF	TPD7106F	TPD7107F
Package	PS-8 (2.8 x 2.9 mm) 	SSOP16 (5.5 x 6.4 mm) 	WSON10A (3 x 3 mm) 
Features	<ul style="list-style-type: none"> Operating power supply voltage range: 5 to 18 V Built-in power supply reverse connection protection function (Supported for power supply reverse connection protection MOSFET applications)	<ul style="list-style-type: none"> Operating power supply voltage range: 4.5 to 27 V Built-in power supply reverse connection protection function (Supported for power supply reverse connection protection MOSFET applications)	<ul style="list-style-type: none"> Operating power supply voltage range: 5.75 to 26 V Current sense output Protective functions; overcurrent, overtemperature, GND disconnect etc. reverse battery connection Diagnosis output; overcurrent, load open, overtemperature etc.

[Return to Block Diagram TOP](#)

4 General purpose small signal MOSFET

SSM3K7002KF / SSM3J168F / SSM3J66MFV

Protection and diagnosis

High efficiency
Low loss

Small size package

Value provided

Wide lineup of small packages contribute to reduce the size and power consumption of system.

1 Small package

A lineup of various small packages such as SOT-723 (VESM 1.2 x 1.2 mm package) is available, contributing to reduce mounting area.

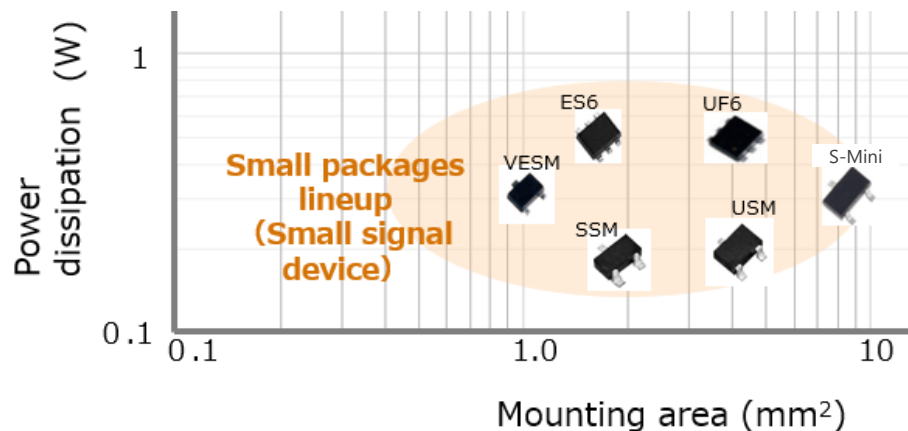
2 Low voltage drive

SSM3J66MFV can be driven at low gate-source voltage of 1.2 V.




3 AEC-Q101 qualified

AEC-Q101 qualified and can be used for various automotive applications.

Small signal package lineup



Line up

Part number	SSM3K7002KF	SSM3J168F	SSM3J66MFV
Package	S-Mini (SOT-346) 	S-Mini (SOT-346) 	VESM (SOT-723) 
V_{DSS} [V]	60	-60	-20
I_D [A]	0.4	-0.4	-0.8
$R_{DS(ON)}$ @ $ V_{GS} = 4.5$ V [Ω]	Typ.	1.2	0.31
	Max	1.75	0.39
Drive voltage [V]	4.5	-4.0	-1.2
Polarity	N-ch	P-ch	P-ch

[Return to Block Diagram TOP](#)

Value provided

Extensive product lineup to meet customers' needs.

1 Extensive lineup of packages

Various packages such as 1-in-1, 2-in-1 are provided and suitable products for circuit board design are selectable.

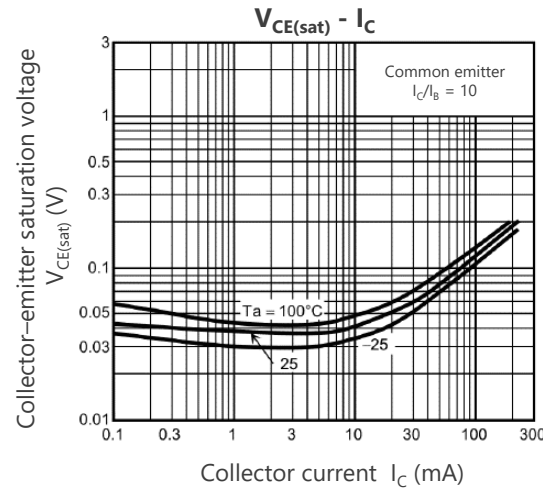
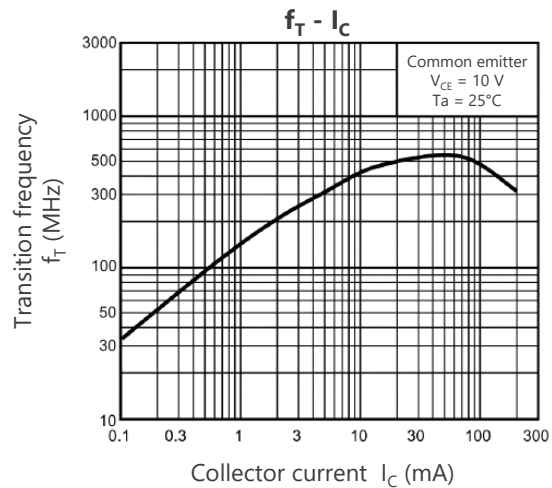
2 Extensive product lineup

Various product lineups, such as general purpose, low noise, low $V_{CE(sat)}$ and high current types are provided. Products can be selected in accordance to the application.

3 AEC-Q101 qualified

AEC-Q101 qualified and can be used for various automotive applications.

Characteristic examples of 2SC2712



Line up

Package			SOT-23F		USM (SOT-323) UFM (SOT-323F)*		S-Mini (SOT-346)	
Classification	$ V_{CE0} $ [V]	$ I_C $ [mA]	NPN	PNP	NPN	PNP	NPN	PNP
General purpose	50	150			2SC4116	2SA1586	2SC2712	2SA1162
	50	500					2SC3325	2SA1313
Low noise	120	100			2SC4117	2SA1587	2SC2713	2SA1163
High current	50	1700				2SA2195*		
	50	2000		TTA501				
	100	2500	TTC501					

[Return to Block Diagram TOP](#)

Value provided

Extensive product lineup to meet customers' needs.

1 Built-in bias resistor type (BRT : Bias Resistor built-in Transistor)

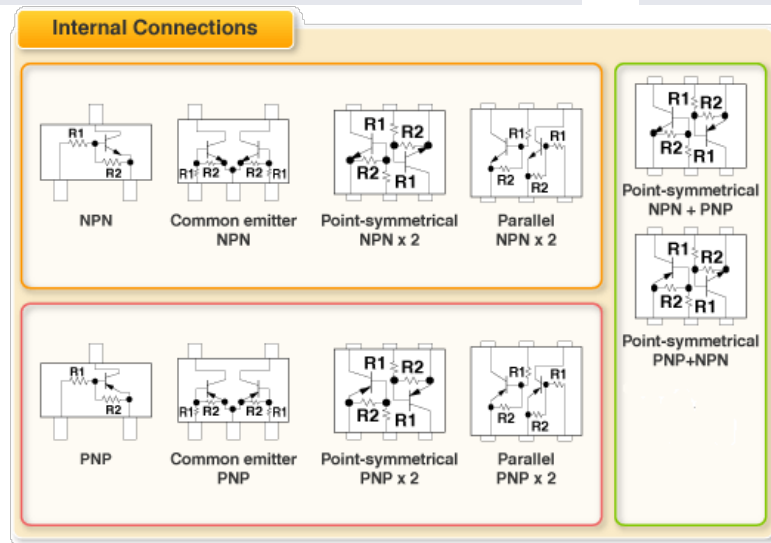
The BRTs contribute to reduction of the number of components, assembly workload and mounting area of circuit boards.

2 Extensive lineup of package and pin assignment

Various package lineups, such as 1-in-1, 2-in-1 and various pin assignment type are provided and suitable products for circuit board design are selectable.

3 AEC-Q101 qualified

AEC-Q101 qualified and can be used for various automotive applications.



Line up

Part number		NPN (BRT)	PNP (BRT)
Package	ES6 (SOT-563)	RN1907FE	RN2907FE
	US6 (SOT-363)	RN1901	RN2901
V_{CE0} (Max) [V]		50	-50
I_C [mA]		100	-100

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7 TVS diode (for CAN communication)

DF3D18FU / DF3D29FU / DF3D36FU

Protection and diagnosis

High efficiency
Low loss

Small size package

Value provided

TVS diodes prevent system damage and malfunction caused by electrostatic discharge (ESD).

1 Improve ESD pulse absorbability

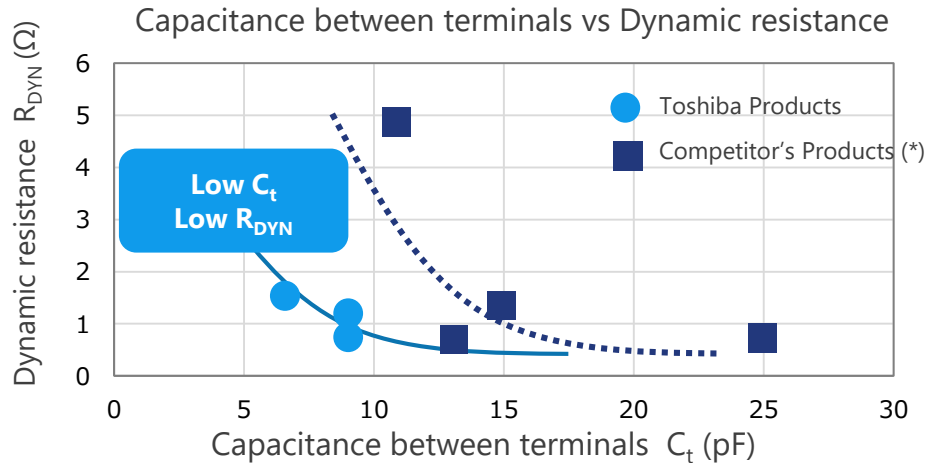
Toshiba proprietary Zener process improves the ESD pulse absorption of TVS diodes.
(Both low dynamic resistance R_{DYN} and low capacitance between terminals C_t)

2 Supports CAN, CAN FD and FlexRay

These are products applicable to in-vehicle LAN communication such as CAN, CAN FD and FlexRay.

3 High ESD immunity


$V_{ESD} > \pm 30$ kV @ ISO 10605
 $V_{ESD} > \pm 20$ kV (L4) @ IEC61000-4-2



(NOTE) : This product is an ESD protection diode and cannot be used for purposes other than ESD protection.

(Based on Toshiba's measurement data)
(*): Measurements of the commercial product

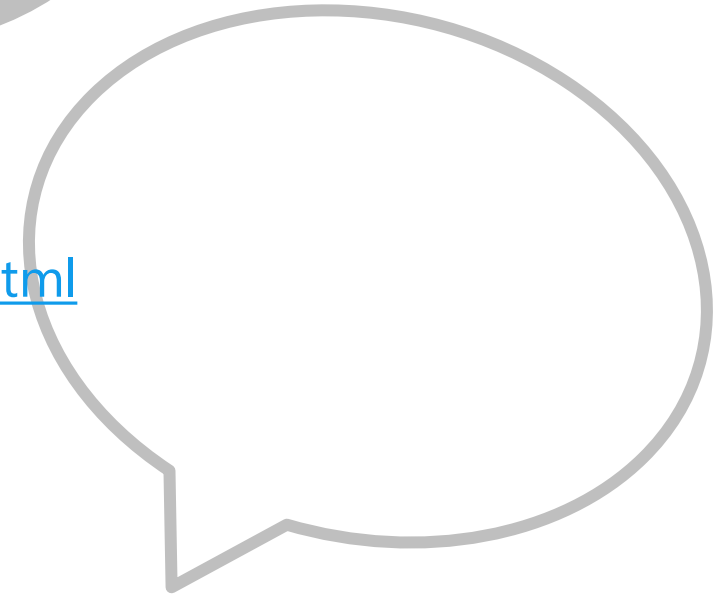
Line up

Part number	DF3D18FU	DF3D29FU	DF3D36FU
Package	USM (SOT-323) 		
V_{ESD} [kV] @ISO 10605	±30	±30	±20
V_{RWM} (Max) [V]	12	24	28
C_t (Typ. / Max) [pF]	9 / 10		6.5 / 8
R_{DYN} (Typ.) [Ω]	0.8	1.1	1.5

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